

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6702xxxxER-G
Typical Mass: 6 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.629	Silicon	104900	7440-21-3
	-	Arsenic	<1	7440-38-2
Lead pad	1.100	Nickel	183400	7440-02-0
	0.087	Silver	14600	7440-22-4
	0.016	Gold	2700	7440-57-5
Die attach	0.018	Epoxy Resin	3000	—
	0.009	Silica	1600	60676-86-0
	0.009	Aluminum oxide	1400	1344-28-1
Bonding wire	0.040	Gold	6700	7440-57-5
Resin	3.682	Silica	613600	60676-86-0
	0.225	Epoxy Resin	37500	—
	0.184	Phenol Resin	30700	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."